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(54) SURFACE ACOUSTIC WAVE DEVICE HAVING A PACKAGE INCLUDING A CONDUCTIVE CAP THAT IS COATED WITH **SEALING MATERIAL** 

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**U.S. Cl.** ...... **257/416**; 257/678; 257/704

257/416; 310/313 R

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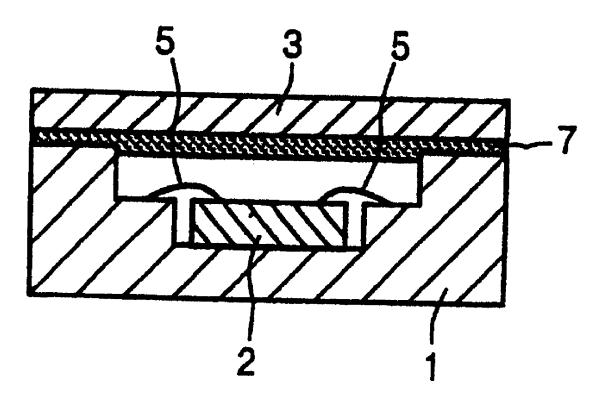
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## **ABSTRACT**

A surface acoustic wave device includes a surface acoustic wave element and a package. The package has a base member and a conductive cap member which are joined together by a sealing material so as to hermetically seal the surface acoustic wave element therein. The conductive cap member is coated with the sealing material on the entire surface thereof that is disposed opposite to the base member.

10 Claims, 2 Drawing Sheets



<sup>\*</sup> cited by examiner